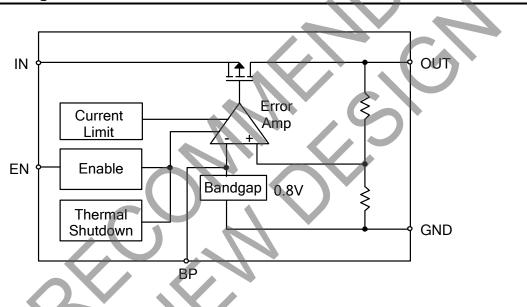


## **Pin Descriptions**

Pin Number	Pin Name	Description		
1	IN	Voltage Input		
2	GND	Ground		
3	EN	Chip Enable Control		
4	BP	Band-Gap Bypass		
5	OUT	Voltage Output		

# **Functional Block Diagram**



# Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	3.5	kV
ESD MM	Machine Model ESD Protection	400	V
VIN	Input Voltage	-0.3 to 5.5	V
V <sub>EN</sub>	EN Pin Voltage	-0.3 to 5.5	V
Vout	Output Voltage	-0.3 to V <sub>IN</sub> +0.3	V
V <sub>BP</sub>	Band Gap Bypass Pin Voltage	-0.3 to 5.5	V
PD	Power Dissipation	500	mW
TJ	Operating Junction Temperature Range	-40 to +125	°C
T <sub>ST</sub>	Storage Temperature Range	-65 to +150	°C



# Recommended Operating Conditions (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Symbol	Parameter	Min	Мах	Unit
V <sub>IN</sub>	Input Voltage	2.5	5.5	V
lout	Output Current	_	150	mA
TA	Operating Ambient Temperature	-40	+85	°C

# **Electrical Characteristics** (@V<sub>CC</sub> = 3.3V, $I_L$ = 30mA, $C_{IN}$ = 1µF, $C_{OUT}$ = 1µF, $T_A$ = +25°C)

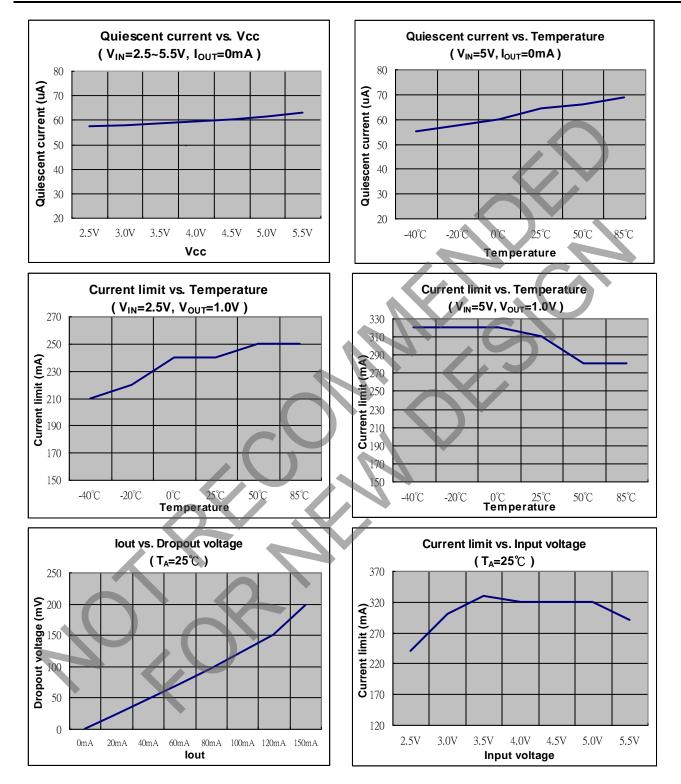
Symbol	Parameter	Conditions	Min	Тур	Max	Unit
System Supply	Input		$\langle \rangle$			
VIN	Operating Input Voltage	I <sub>L</sub> = 0 to 150mA	2.5	-	5.5	V
$\Delta V_{OUT}/V_{OUT}$	Output Voltage Accuracy	$V_{IN} = V_{OUT} + 1V$ where 1mA $\leq I_{OUT} \leq 50$ mA	-2		2	%
V <sub>DO</sub>	Dropout Voltage	I <sub>L</sub> = 150mA	—	200	300	mV
I <sub>OUT</sub>	Output Current	$V_{IN} - V_{OUT} = 1V$	150	-		mA
Ι <sub>Q</sub>	Quiescent Current	$V_{IN} = V_{OUT} + 1V$ where $I_{OUT} = 0$ and $V_{EN} = V_{IN}$	G	50	80	μA
ISHUTDOWN	Shutdown Current	$V_{IN} = V_{OUT} + 1V$ where $I_{OUT} = 0$ and $V_{EN} = 0$		0.1	1	μA
PSRR	Power Supply Rejection Ratio	I <sub>OUT</sub> = 30mA, f = 1kHz		70		dB
ILIMIT	Current Limit	F	200	250		mA
Thermal Manag	ement					
T <sub>SHUTDOWN</sub>	Thermal Shutdown		_	+150		°C
Reference Volta	ige					
$\Delta V_{REF} / \Delta T$	Tempco of Bandgap Reference		_	30	50	ppm/°C
$\Delta V_{OUT} / \Delta T$	Tempco of Output Voltage	$I_{OUT} = 30 \text{mA}, -40^{\circ}\text{C} \le T_{\text{A}} \le +85^{\circ}\text{C}$	_	50	100	ppm/°C
Control and Pro	tection					
V <sub>IH,EN</sub>	-	_	2.0	_	_	V
V <sub>IL,EN</sub>	- /		_	_	0.7	V
	EN Pin Leakage Current	$V_{EN} = V_{IN} @ V_{IN} = 5.0V$ and $V_{SS} = 0V$	_	0.01	0.1	μA
I <sub>EN</sub>		$V_{EN} = V_{SS} @V_{IN} = 5.0V$ and $V_{SS} = 0V$	_	0.01	0.1	μA
Regulation						
ΔV <sub>O</sub> /ΔV <sub>IN</sub>	Line Regulation	$V_{OUT}$ + 0.5V $\leq$ $V_{IN} \leq$ 5.5V where $V_{OUT}$ > 2.0V, $I_{OUT}$ = 30mA	_	0.02	0.1	%/V
	Load Regulation	$1mA \le I_L \le 150mA$ where $V_{IN} = V_{OUT} + 1V$	_	0.003	0.006	%/mA
Noise						
e <sub>n</sub>	Output Noise	BW = 10Hz to 100kHz	_	50	_	μV <sub>rms</sub>
Thermal Resista	ance					
2	Thermal Resistance Junction-to-	SOT25 (Note 4)	_	200	_	°C/W
$\theta_{JA}$	Ambient	SOT353 (Note 4)	_	337	_	°C/W
•	Thermal Resistance Junction-to-	SOT25 (Note 4)	_	52	_	°C/W
$\theta_{\rm JC}$	Case	SOT353 (Note 4)	_	121	_	°C/W

Note: 4. Test condition for SOT25 and SOT353: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



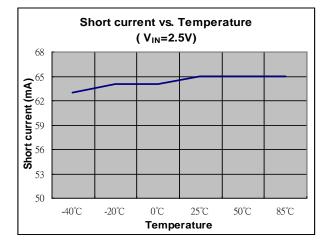
AP7115

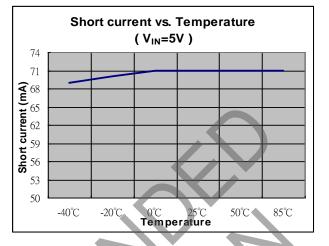
## **Typical Operating Characteristics**





## **Typical Operating Characteristics (Cont.)**

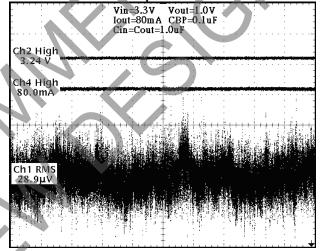


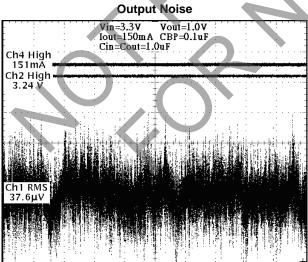




	Vin=3.3V Iout=10mA Cin=Cout=1	Vout=1.0V CBP=0.1uF .0uF		· · · · · · · · ·
Ch2 High 3.24 V				
		· · · · · · · · · · · · · · · · · · ·	· · · · · · · · · · · · · · · · · · ·	
Ch4 High 10.0mA				
Ch1 RMS 20.0µV				

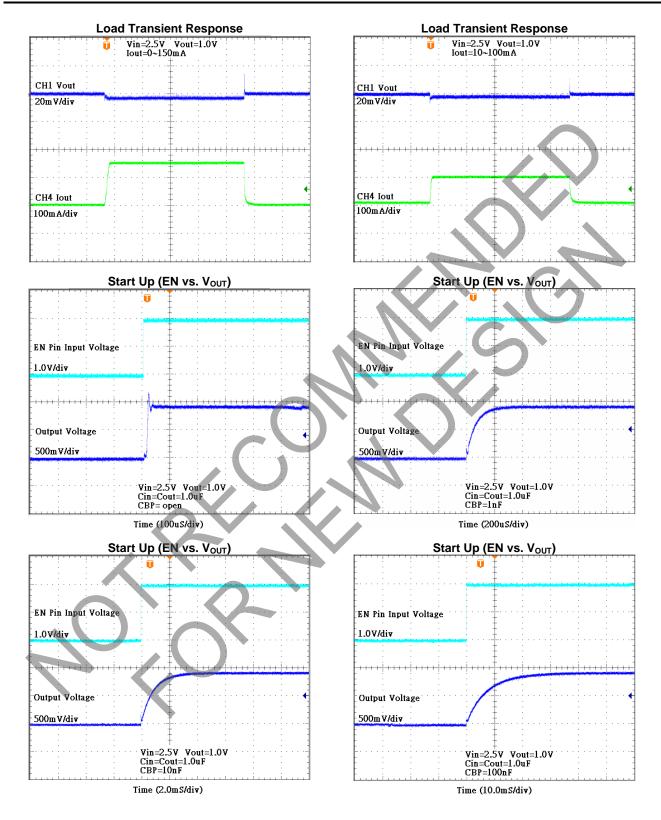








## Typical Operating Characteristics (Cont.)





### Application Note

#### Input Capacitor

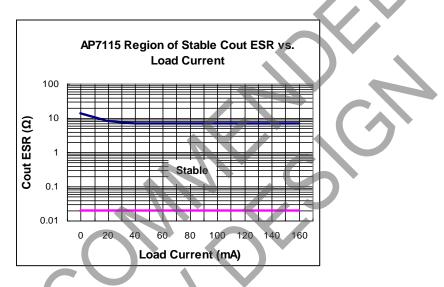
A 1µF input capacitor is required between the AP7115 input pin and GND.

There are no requirements for the ESR on input capacitor, but tolerance and temperature coefficient must be considered.

#### **Output Capacitor**

The AP7115 can work with very small ceramic output capacitors (1µF or greater). Higher capacitance values help to improve transient. The output capacitor's ESR is critical because it from a zero to provide phase lead which is required for loop stability.

Figure below is Cout ESR vs. Load Current.



### Band-Gap Bypass Capacitor

0.1µF bypass capacitor Between BP pin and GND can reduce output voltage noise.

### **Shutdown Input Operation**

The AP7115 is shutdown by pulling the EN pin low, and turned on by driving the input high. If the shutdown feature is not required, the EN pin should be tied to VIN to keep the regulator on at all time.

#### Dropout Voltage

VDROPOUT = VIN - VOUT = RDS(ON) × IOUT

### **Current Limit**

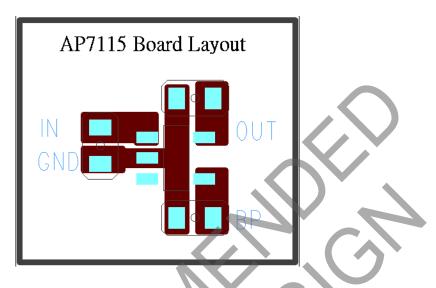
The AP7115 monitors and controls the PMOS' gate voltage, limiting the output current to 250mA (typ.). The output can be shorted to ground for an indefinite period of time without damaging the part.



### Application Note (Cont.)

#### PCB Layout

Optimum performance can only be achieved when the device is mounted on a PC board according to the diagram below:



#### **Thermal Considerations**

Thermal Shutdown Protection limits power dissipation in AP7115. When the operation junction temperature exceeds +155°C, the Over Temperature Protection circuit starts the thermal shutdown function and turns the pass element off. The pass element turns on again after the junction temperature cools by +30°C. For continuous operation, do not exceed absolute maximum operation junction temperature +125°C. The power dissipation definition in device is:

 $P_{D} = (V_{IN} - V_{OUT}) \times I_{OUT} + V_{IN} \times I_{Q}$ 

The maximum power dissipation depends on the thermal resistance of IC package, PCB layout, the rate of surroundings airflow and temperature difference between junction to ambient. The maximum power dissipation can be calculated by the following formula:

 $P_{D(MAX)} = (T_{J(MAX)} - T_A) / \theta_{JA}$ 

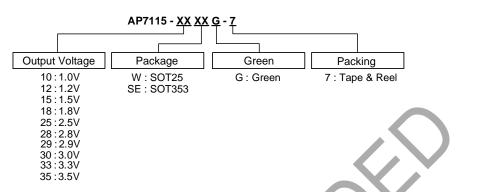
Where  $T_{J(MAX)}$  is the maximum operation junction temperature +125°C,  $T_A$  is the ambient temperature and the  $\theta_{JA}$  is the junction to ambient thermal resistance.





AP7115

### Ordering Information

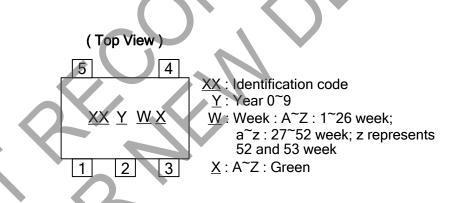


Dent Number	Beelkere Code	Packaging	7" Tape and Reel		
Part Number	Package Code	(Note 5)	Quantity	Part Number Suffix	
AP7115-XXWG-7	W	SOT25	3000/Tape & Reel	-7	
AP7115-XXSEG-7	SE	SOT353	3000/Tape & Reel	-7	

Notes: 5. Pad layout as shown in Diodes Incorporated's package outline PDFs, which can be found on our website at http://www.diodes.com/package-outlines.html.

### **Marking Information**

SOT25/SOT353



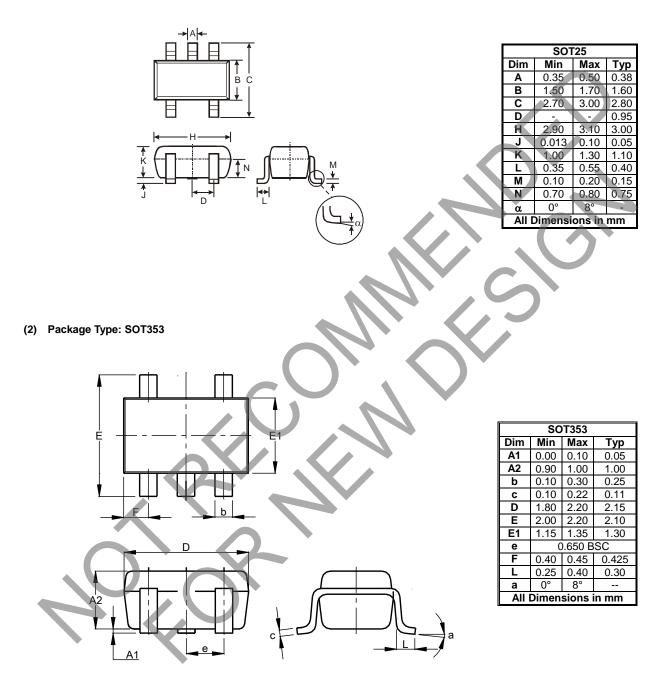
Part Number	Identification Code	Part Number	Identification Code	
SOT25		SOT353		
AP7115-10WG-7	FO	AP7115-10SEG-7	GO	
AP7115-12WG-7	FP	AP7115-12SEG-7	GP	
AP7115-15WG-7	FQ	AP7115-15SEG-7	GQ	
AP7115-18WG-7	FR	AP7115-18SEG-7	GR	
AP7115-25WG-7	FS	AP7115-25SEG-7	GS	
AP7115-28WG-7	FT	AP7115-28SEG-7	GT	
AP7115-29WG-7	FU	AP7115-29SEG-7	GU	
AP7115-30WG-7	FV	AP7115-30SEG-7	GV	
AP7115-33WG-7	FW	AP7115-33SEG-7	GW	
AP7115-35WG-7	FX	AP7115-35SEG-7	GX	



### **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### (1) Package Type: SOT25





Dimensions

Ζ

G

Х

Y

C1

C2

Value 3.20

1.60

0.55

0.80

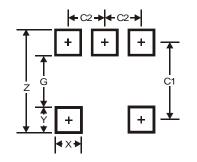
2.40

0.95

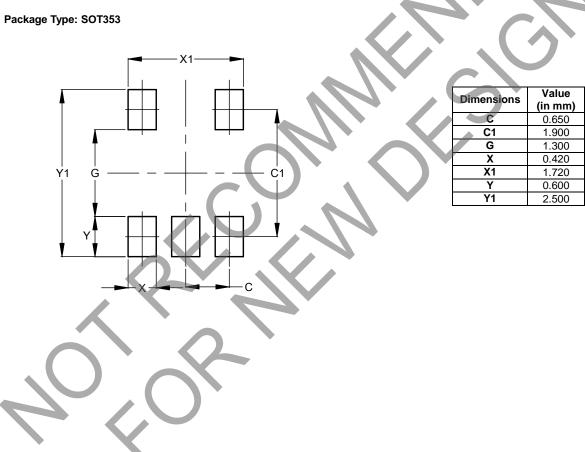
## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

### (1) Package Type: SOT25



(2) Package Type: SOT353





AP7115

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